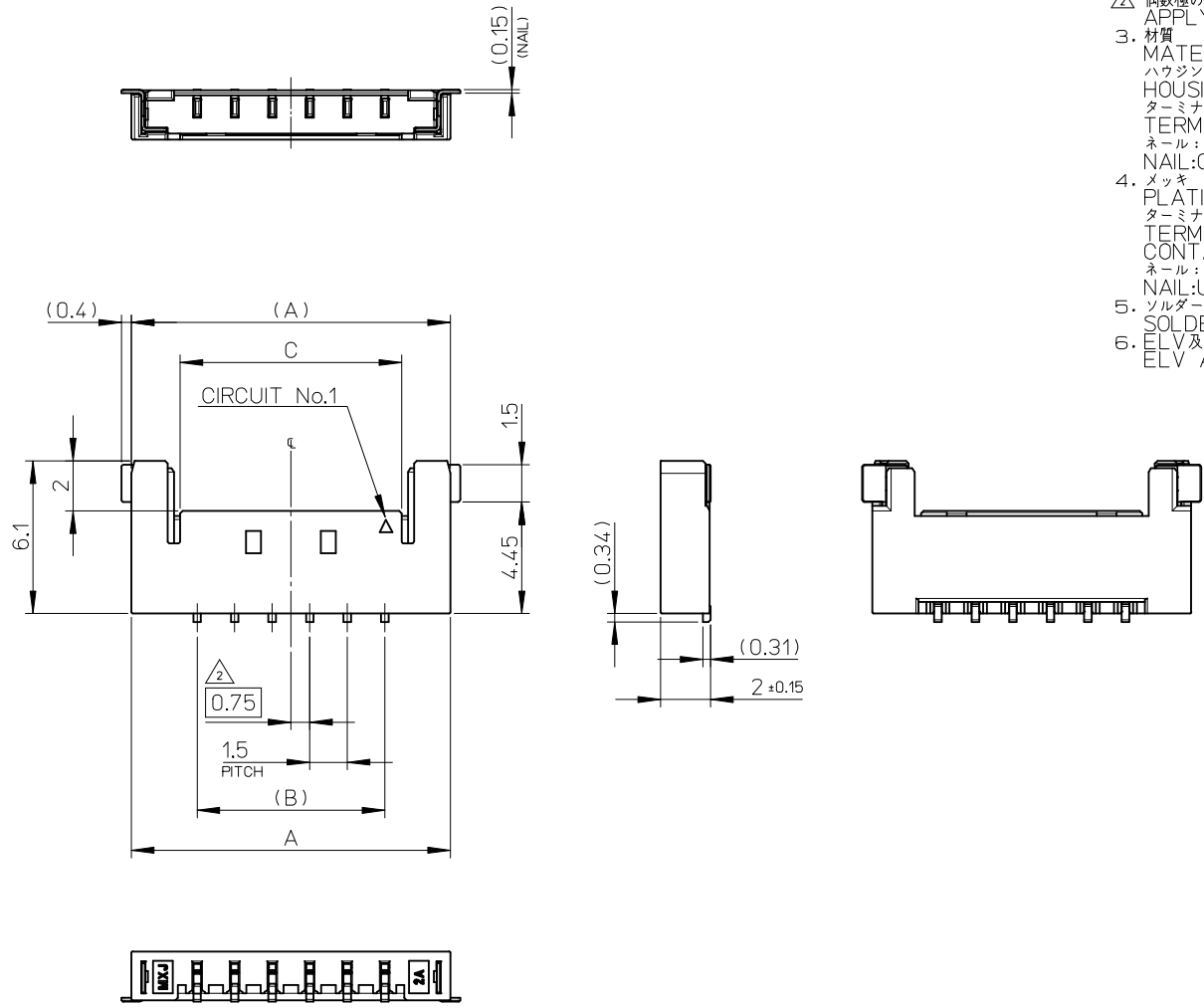


NOTE.

- 嵌合相手: 504051\*\*\*\*  
MATE WITH: 504051\*\*\*\*  
△ 偶数極の製品に適用  
APPLY EVEN CIRCUIT PRODUCTS.
- 材質  
MATERIAL  
ハウジング: 耐熱性樹脂 UL94-V0 BLACK  
HOUSING: HEATPROOF RESIN UL94-V0 BLACK  
ターミナル: 銅合金  
TERMINAL: COPPER ALLOY  
ネール: 銅合金  
NAIL: COPPER ALLOY
- メッキ  
PLATING  
ターミナル: 下地 Niメッキ 1μm MIN., コンタクト・半田付け部 Auメッキ 0.1μm MIN.  
TERMINAL: UNDER NICKEL PLATING 1μm MIN.  
CONTACT AND TAIL GOLD PLATING 0.1μm MIN.  
ネール: 下地 Niメッキ 1μm MIN., Snメッキ 1μm MIN.  
NAIL: UNDER NICKEL PLATING 1μm MIN., TIN PLATING 1μm MIN.
- ソルダーテイルとネールの平坦度: 0.08mm MAX.  
SOLDER TAIL AND FITTING NAIL COPLANARITY: 0.08mm MAX.
- ELV及びRoHS適合品  
ELV AND RoHS COMPLIANT.



17.85	16.5	21.75	5040501291	12
14.85	13.5	18.75	5040501091	10
11.85	10.5	15.75	5040500891	8
10.35	9.0	14.25	5040500791	7
8.85	7.5	12.75	5040500691	6
7.35	6.0	11.25	5040500591	5
5.85	4.5	9.75	5040500491	4
C	B	A	EMBOSSED PACKAGE	CIRCUIT
			ORDER No.	
CONNECTOR SERIES No. : 504050**91				

REVISED EC NO: J2016-0297 DRWN: TAKAIKE 2015/09/18 CHKD: KASAKAWA 2015/10/02 APPR: NUKITA 2015/10/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	0.25 UNDER ±0.03		MM ONLY		5:1	METRIC	
	0.25 OVER 0.5 UNDER ±0.05		DRAWN BY DATE		TITLE		
	0.5 OVER 1.0 UNDER ±0.1		THANYU 2012/03/29		1.5 WIRE TO BOARD CONN. R/A H=2MM HEADER ASS'Y		
	1.0 OVER 10 UNDER ±0.2		CHECKED BY DATE		molex		
10 OVER 30 UNDER ±0.25		KASAKAWA 2012/03/29		APPROVED BY DATE		DOCUMENT NO.	SHEET NO.
30 OVER ±0.3		Y01TO 2012/04/18		MATERIAL NO.		SD-504050-001	1 OF 2
ANGULAR ±3 °		SEE CHART		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3					

10 9 8 7 6 5 4 3 2 1

F

E

D

C

B

A

F

E

D

C

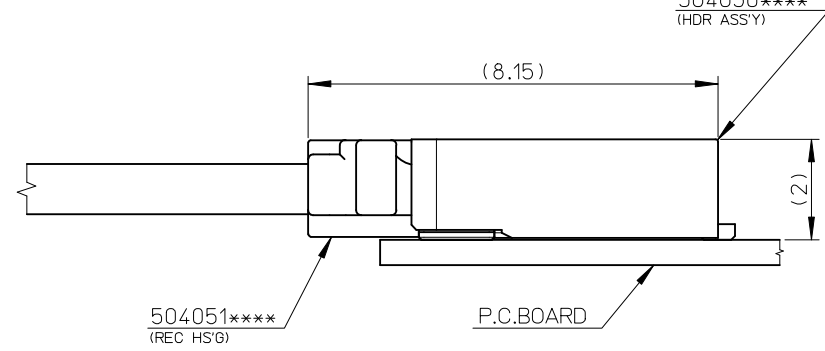
B

A

504050\*\*\*\*  
(HDR ASS'Y)

(8.15)

(2)

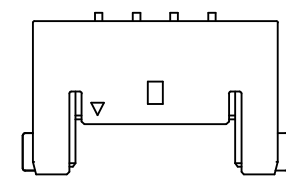


504051\*\*\*\*  
(REC HS'G)

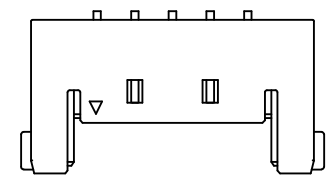
P.C. BOARD

MATED CONNECTORS

NUMBER of LOCK Ⓞ

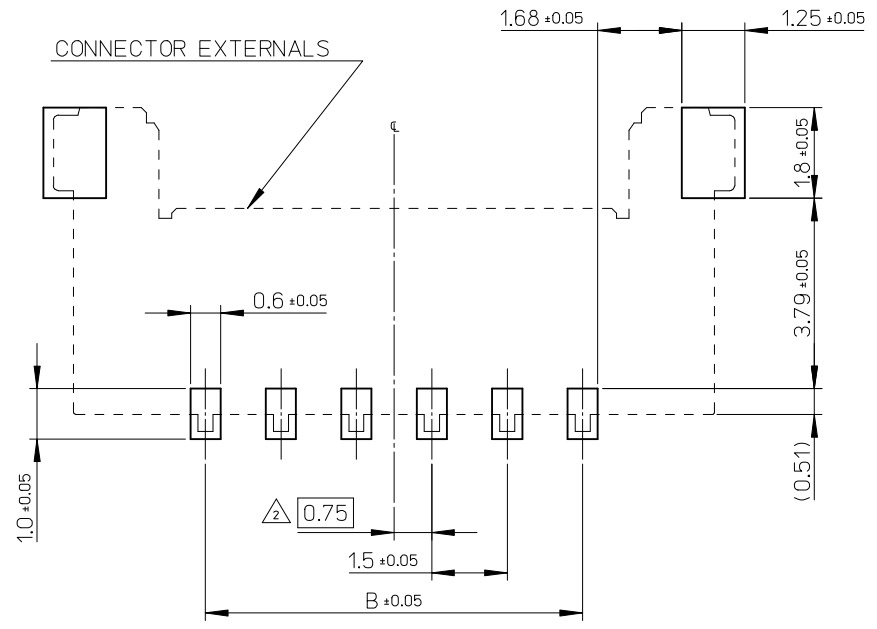


4 CIRCUITS



5-12 CIRCUITS

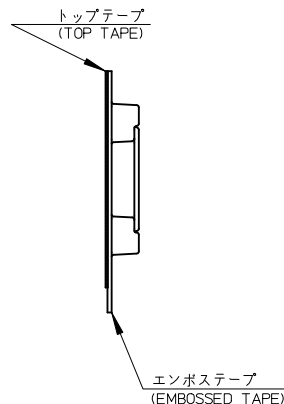
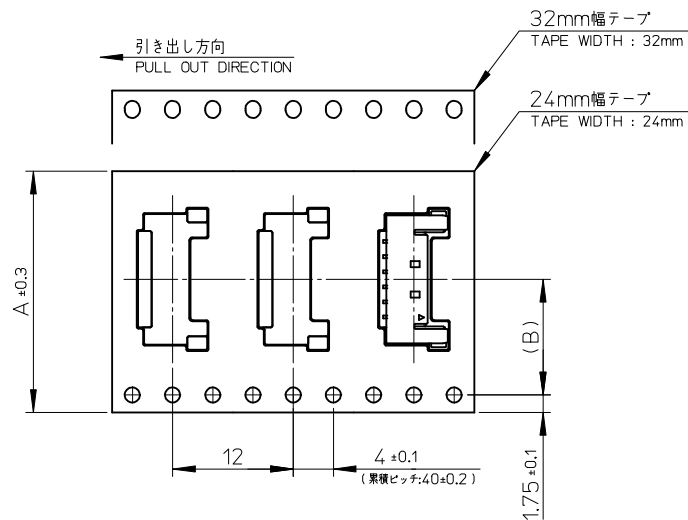
CONNECTOR EXTERNALS



RECOMMENDED PATTERN LAYOUT (REF.)

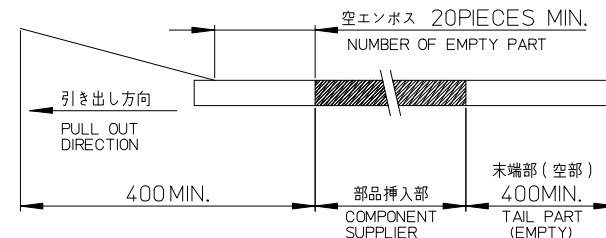
REVISED EC NO: J2016-0297 G DRWN: TAKAIKE 2015/09/18 CHKD: KASAKAWA 2015/10/02 APPR: NUKITA 2015/10/02	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	± 0.03	DRAWN BY THANYU	DATE 2012/03/29	TITLE 1.5 WIRE TO BOARD CONN. R/A H=2MM HEADER ASS'Y		
	0.25 OVER 0.5 UNDER	± 0.05	CHECKED BY KASAKAWA	DATE 2012/03/29			
	0.5 OVER 1.0 UNDER	± 0.1	APPROVED BY YOITO	DATE 2012/04/18			
1.0 OVER 10 UNDER	± 0.2	MATERIAL NO.		DOCUMENT NO.	SHEET NO.		
10 OVER 30 UNDER	± 0.25	SEE CHART		SD-504050-001	2 OF 2		
30 OVER	± 0.3	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
ANGULAR	± 3 °	SIZE A3					

9 8 7 6 5 4 3 2 1



NOTE

1. 梱包数量: 2700個 / リール  
NUMBER OF CONNECTORS : 2700 PIECES/REEL
2. リードテープ長さ  
LEAD TAPE LENGTH

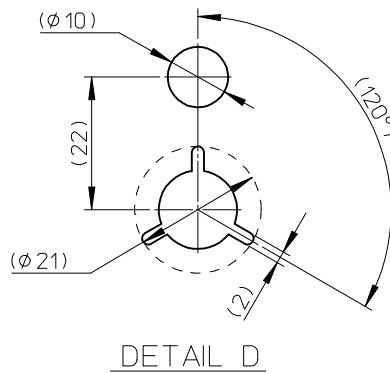
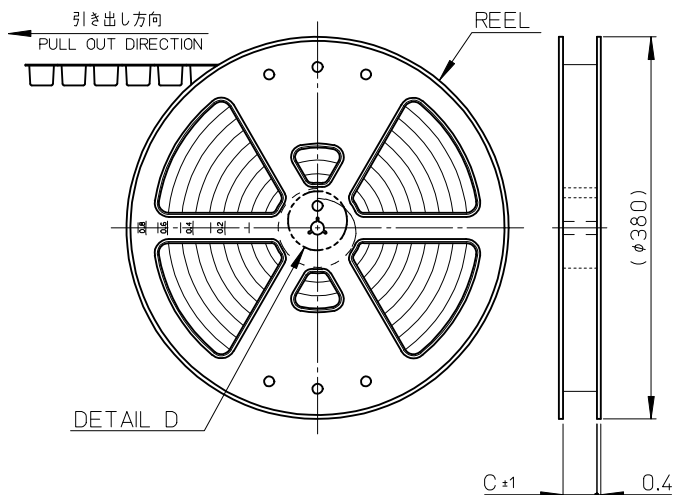


3. 材料  
MATERIALS  
キャリアテープ: ポリスチレン  
CARRIER TAPE : POLYSTYRENE  
トップテープ: ポリエステル, ポリエチレン, ポリエチレンテレフタレート  
TOP TAPE : POLYESTER, POLYETHLENE, POLYETHYLENE TEREPHTHALATE  
リール: ポリスチレン (リサイクル材を含む)  
REEL : POLYSTYRENE (RECYCLE MATERIAL CONTAINED)

4. 製品詳細寸法については、RSD-504050-001を参照して下さい。  
PLEASE REFER TO RSD-504050-001 FOR THE DETAILED DIMENSION OF THE CONNECTOR.

5. ELV及びRoHS適合品  
ELV AND RoHS COMPLIANT.

6. トップテープの剥離強度については、IEC60286-3に準拠の事。  
TOP TAPE PEEL FORCE IS DEFINED BY IEC60286-3.



45.5	20.2	44	5040501291	12
33.5	14.2	32	5040501091	10
33.5	14.2	32	5040500891	8
25.5	11.5	24	5040500791	7
25.5	11.5	24	5040500691	6
25.5	11.5	24	5040500591	5
25.5	11.5	24	5040500491	4
C	B	A	ORDER No.	CIRCUIT
WIDTH OF TAPE				

REVISED EC NO: J2015-1139 2015/03/05 DRWNK:CHIKANO 2015/03/05 CHKD:KASAKAWA 2015/03/05 APPR:NUKITA 2015/03/06	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		0.25 UNDER	±0.03	DRAWN BY THANYU	DATE 2012/03/29	TITLE EMBOSSED TAPE PACKAGE FOR 504050-**** (1.5 W/B CONN. H=2MM) <b>molex</b> DOCUMENT NO. SD-504050-002 SHEET NO. 1 OF 1			
		0.25 OVER 0.5 UNDER	±0.05	CHECKED BY KASAKAWA	DATE 2012/03/29				
		0.5 OVER 1.0 UNDER	±0.1	APPROVED BY YOITO	DATE 2012/04/18				
1.0 OVER 10 UNDER	±0.2	MATERIAL NO.							
10 OVER 30 UNDER	±0.25	ANGULAR ±3 °		SEE CHART					
30 OVER	±0.3	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				